

CLAIMS (with indication of amended or new):

6. (NEW) A method of removing an electromagnetic shielding case from a circuit substrate, said shielding case comprising a cover section for covering electronic components mounted on said circuit substrate; a plurality of leg sections for attaching said cover section to said circuit substrate, each of said leg sections protruding from said cover section toward said substrate and being inserted in through-holes provided in said substrate; and a plurality of tool-insertion openings provided in said cover section, said tool-insertion openings corresponding to respective ones of said leg sections;

said method comprising the steps of:

for each of said leg sections, inserting a cutting tool into a corresponding said tool-insertion opening, and cutting the corresponding leg section away from said cover section with said cutting tool; and

after all of leg sections have been cut away, removing the cover section.

7. (NEW) The method of claim 6, further comprising the step of removing the cut-away leg sections from the circuit substrate.

8. (NEW) The method of claim 7, wherein said leg sections are soldered to the circuit substrate, further comprising the step of melting the solder fixing the leg sections to the circuit substrate and thereby removing the leg portions from the circuit substrate.

9. (NEW) The method of claim 6, wherein each of said leg sections has a corresponding pair of said tool-inserting openings, and said cutting step comprises the step of using said cutting tool to cut from one to the other of said pair of openings.

10. (NEW) A method of removing an electromagnetic shielding case from a circuit substrate, said shielding case comprising a cover section for covering electronic components mounted on said circuit substrate; a plurality of leg sections for attaching said cover section to said circuit substrate, each of said leg sections protruding from said cover section toward said

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substrate and being inserted in through-holes provided in said substrate; said method comprising the steps of:

providing a plurality of tool-insertion openings in said cover section, said tool-insertion openings corresponding to respective ones of said leg sections;

for each of said leg sections, inserting a cutting tool into a corresponding said tool-inserting opening, and cutting the corresponding leg section away from said cover section with said cutting tool; and

after all of leg sections have been cut away, removing the cover section.

11. (NEW) The method of claim 10, further comprising the step of removing the cut away leg sections from the circuit substrate.

12. (NEW) The method of claim 11, wherein said leg sections are soldered to the circuit substrate, further comprising the step of melting the solder fixing the leg sections to the circuit substrate and thereby removing the leg portions from the circuit substrate.

13. (NEW) The method of claim 10, wherein each of said leg sections is provided with a corresponding pair of said tool-inserting openings, and said cutting step comprises the step of using said cutting tool to cut from one to the other of said pair of openings.

14. (NEW) The method of claim 13, further comprising the step of providing a respective cutout from each of said tool-inserting openings to an edge of said cover section, said cutout partially defining the corresponding said leg portion.

15. (NEW) The method of claim 10, further comprising the step of providing a respective cutout from each of said tool-inserting openings to an edge of said cover section, said cutout partially defining the corresponding said leg portion.

16. (NEW) The method of making an electromagnetic shielding case removable from a circuit substrate, said shielding case comprising a cover section for covering electronic

components mounted on said circuit substrate; a plurality of leg sections for attaching said cover section to said circuit substrate, each of said leg sections protruding from said cover section toward said substrate and being inserted in through-holes provided in said substrate; said method comprising the steps of:

providing a plurality of tool-insertion openings in said cover section, said tool-insertion openings corresponding to respective ones of said leg sections;

whereby for each of said leg sections a cutting tool can be inserted into a corresponding said tool-insertion opening and utilized to cut the corresponding leg section away from said cover section, so as to permit all of said leg sections to be cut away and said cover section to be removed.

17. (NEW) The method of claim 16, wherein each of said leg sections is provided with a corresponding pair of said tool-inserting openings, whereby said cutting tool can be utilized to cut from one to the other of said pair of openings.

18. (NEW) The method of claim 17, further comprising the step of providing a respective cutout from each of said tool-inserting openings to an edge of said cover section, said cutout partially defining the corresponding said leg portion.

19. (NEW) The method of claim 16, further comprising the step of providing a respective cutout from each of said tool-inserting openings to an edge of said cover section, said cutout partially defining the corresponding said leg portion.